

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	3	("20020113034" "20030092195" "20030224531").PN.	US-PGPUB; USPAT	ADJ	ON	2008/09/22 07:16
S3	853	(422/82.01).CCLS.	US-PGPUB; USPAT	OR	OFF	2008/09/22 07:50
S5	83	S3 and microfluidic	US-PGPUB; USPAT	ADJ	ON	2008/09/22 07:50
S6	67	S5 and electrode	US-PGPUB; USPAT	ADJ	ON	2008/09/22 07:50
S7	7	S6 and (electrospray or nebuliz\$5)	US-PGPUB; USPAT	ADJ	ON	2008/09/22 07:51
S8	20451	microfluid\$ or (lab near4 chip)	US-PGPUB; USPAT	ADJ	ON	2008/09/22 07:54
S9	3928	S8 and (electrospray or nozzle)	US-PGPUB; USPAT	ADJ	ON	2008/09/22 07:54
S10	1896	S9 and electrode	US-PGPUB; USPAT	ADJ	ON	2008/09/22 07:54
S11	923	S10 and (lid or cover)	US-PGPUB; USPAT	ADJ	ON	2008/09/22 07:55
S12	419	S11 and semiconductor	US-PGPUB; USPAT	ADJ	ON	2008/09/22 07:56
S13	335	S11 and dop\$5	US-PGPUB; USPAT	ADJ	ON	2008/09/22 07:56
S14	162	S13 and (MEMS or microstructure\$)	US-PGPUB; USPAT	ADJ	ON	2008/09/22 07:59
S15	61	("4908112" "5073239" "5092973" "5110431" "5132012" "5141621" "5180480" "5250263" "5296114" "5376252" "5480112" "5630924" "5705813" "5872010" "Re34757").PN. OR ("6110343").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/22 08:05
S16	19664	electrospray	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/22 08:21
S17	2290	S16 and MEMS	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/22 08:21
S18	817	S17 and (lid or cover)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/22 08:21

S19	145	S18 and semiconductor	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/22 08:23
S20	1	"6523762".pn.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/22 09:19
S21	1	"5632876".pn.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/22 10:12
S22	1	"5750015".pn.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/22 10:14
S23	1	"5858188".pn.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/22 10:15
S24	1	"6007690".pn.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/22 10:15
S25	0	2003/224531 A1	US-PGPUB; USPAT	ADJ	ON	2008/09/22 10:25
S27	20880	electrospray	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/09/22 10:36
S28	1093	S27 and microfluid\$	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/09/22 10:37
S29	246	S28 and MEMS	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/09/22 10:37
S30	148	S29 and (lid or cover)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/09/22 10:37
S31	20451	microfluid\$ or (lab near4 chip)	US-PGPUB; USPAT	ADJ	ON	2008/09/22 14:41
S32	3928	S31 and (electrospray or nozzle)	US-PGPUB; USPAT	ADJ	ON	2008/09/22 14:41
S33	1896	S32 and electrode	US-PGPUB; USPAT	ADJ	ON	2008/09/22 14:41
S34	20	S33 and ((lid or cover) near (conduct\$4 or semiconduct\$4))	US-PGPUB; USPAT	ADJ	ON	2008/09/22 14:41
S35	32	(436/102).CCLS.	US-PGPUB; USPAT	OR	OFF	2008/09/22 15:50

S36	1736	(436/180).CCLS.	US-PGPUB; USPAT	OR	OFF	2008/09/22 15:51
S37	649	(436/149).CCLS.	US-PGPUB; USPAT	OR	OFF	2008/09/22 15:51

9/22/2008 3:52:37 PM

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